



## The correct cleaner for lead-free solder pastes Stencil Cleaning

Product recommendation for the removal of unsoldered **HERAEUS** solder pastes

Solder paste	VIGON®			ZESTRON®			ATRON®
	SC	SC 200	SC 202	SD 301	SD 100	VD	SP 200
Heraeus F 365 Cu0.5-89.0 M30	+	+	+	+	+	+	+
Heraeus F360 Ag3.5-89.0 L25	+	+	+	+	+	+	+
Heraeus F380 Ag3.5-90.0 L25	+	+	+	+	+	+	+
Heraeus F 369 CUO. 5-89M3	+	+	+	+	+	+	+

- + easily removable
- 0 removable with process optimization (e.g. with additives and / or longer cleaning time)
- hardly removable – try alternative cleaners

Test conditions for VIGON® SC (unsoldered paste):

- Spray-in-air process, stencil cleaning application
- Cleaning at 45°C, 3-6 minutes

Test conditions for VIGON® SC 200, VIGON® SC 201, ZESTRON® SD 300, ZESTRON® SD 100, ZESTRON® VD, ATRON® SP 200 (unsoldered paste):

- Spray-in-air process, stencil cleaning application
- Cleaning at 25°C, 3-6 minutes

**ZESTRON®**

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